ABSTRACT

ASSEMBLY OF AN OPTO-ELECTRONIC ENGINE

In the present disclosure, the problem associated with single layer assembly is solved by using a multi-layer assembly. First layer comprises a FPGA and optics on a high accuracy substrate to enable optical alignment. Second layer comprises an interposer or a substrate that can dissipate the high amount of heat generated by the digital circuits and the third layer comprises low cost organic analog interposer.

Figure 5